

APPLICATIONS

- ✧ Cell Phone Handsets and Accessories.
- ✧ Microprocessor based equipment.
- ✧ Personal Digital Assistants (PDA's).
- ✧ Notebooks, Desktops, and Servers.
- ✧ Portable Instrumentation.
- ✧ Peripherals.
- ✧ USB Interface.

IEC COMPATIBILITY

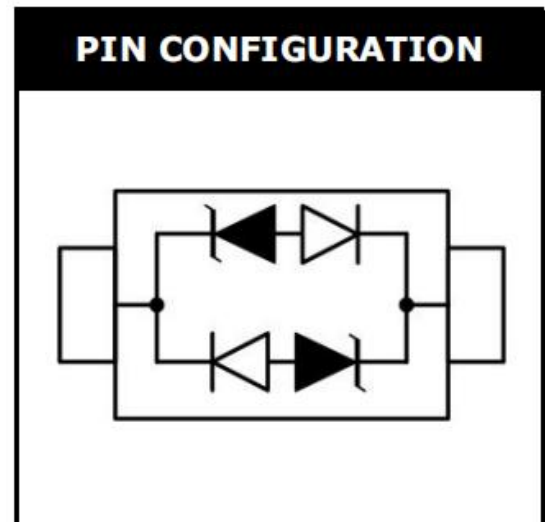
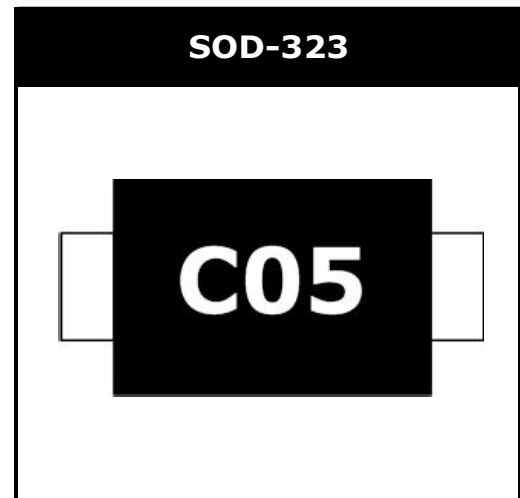
- ✧ IEC61000-4-2 (ESD) $\pm 30\text{kV}$ (air), $\pm 15\text{kV}$ (contact).
- ✧ IEC61000-4-4 (EFT) 40A (5/50 77 s).
- ✧ IEC61000-4-5 (Lightning) 20A (8/20 μs).

FEATURES

- ✧ 350 Watts Peak Pulse Power per Line ($t_p=8/20\mu\text{s}$).
- ✧ Protects one I/O line (bidirectional).
- ✧ Low clamping voltage.
- ✧ Working voltages: 3V, 5V, 8V, 12V, 15V, 24V.
- ✧ Low leakage current.

MECHANICAL CHARACTERISTICS

- ✧ JEDEC SOD-323 Package.
- ✧ Molding Compound Flammability Rating : UL 94V-O.
- ✧ Weight 5 Milligrams (Approximate).
- ✧ Quantity Per Reel : 3,000pcs.
- ✧ Reel Size : 7 inch.



DEVICE CHARACTERISTICS
MAXIMUM RATINGS (@ 25°C Unless Otherwise Specified)

PARAMETER	SYMBOL	VALUE	UNITS
Peak Pulse Power (tp=8/20μs waveform)	P _{PP}	350	Watts
Lead Soldering Temperature	T _L	260 (10 sec.)	°C
Operating Temperature Range	T _J	-55 ~ 150	°C
Storage Temperature Range	T _{STG}	-55 ~ 150	°C

ELECTRICAL CHARACTERISTICS PER LINE (@ 25°C Unless Otherwise Specified)

PART NUMBER	DEVICE MARKING	V _{RWM}	V _B	I _T	V _C	V _C		I _R	C _T
		(V) (max.)	(V) (min.)	(mA)	@1A (max.)	(max.)	(@A)	(μA) (max.)	(pF) (typ.)
LC03CI	cc	3.3	4.0	1	5.15	13.9	8	40	0.4
LC05CI	AL	5.0	6.0	1	9.80	18.3	8	5	0.4
LC08CI	BC	8.0	8.5	1	13.40	18.5	8	2	0.4
LC12CI	DC	12.0	13.3	1	19.00	28.6	6	1	0.4
LC15CI	EC	15.0	16.7	1	24.00	31.8	5	1	0.4
LC24CI	HC	24.0	26.7	1	43.00	56.0	3	1	0.4

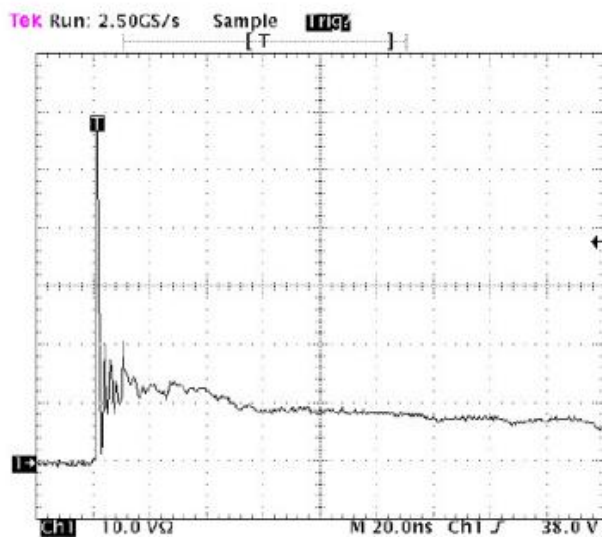


Figure 1. ESD Clamping Voltage Screenshot
Positive 8 kV contact per IEC 61000-4-2

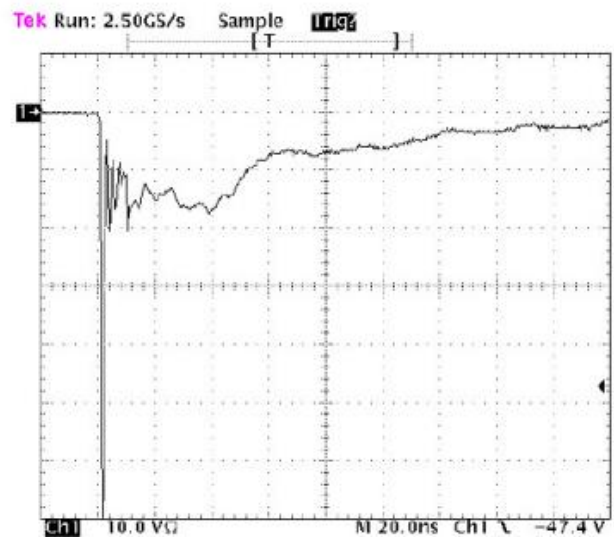
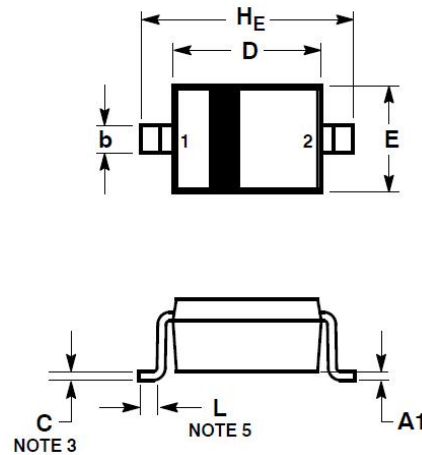
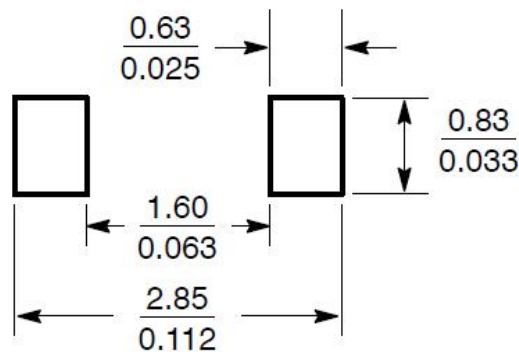


Figure 2. ESD Clamping Voltage Screenshot
Negative 8 kV contact per IEC 61000-4-2

SOD-323 PACKAGE OUTLINE & DIMENSIONS

NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. LEAD THICKNESS SPECIFIED PER L/F DRAWING WITH SOLDER PLATING.
4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
5. DIMENSION L IS MEASURED FROM END OF RADIUS.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.80	0.90	1.00	0.031	0.035	0.040
A1	0.00	0.05	0.10	0.000	0.002	0.004
A3	0.15 REF			0.006 REF		
b	0.25	0.32	0.4	0.010	0.012	0.016
C	0.089	0.12	0.177	0.003	0.005	0.007
D	1.60	1.70	1.80	0.062	0.066	0.070
E	1.15	1.25	1.35	0.045	0.049	0.053
L	0.08			0.003		
H _E	2.30	2.50	2.70	0.090	0.098	0.105

*** SOLDERING FOOTPRINT**


Website: <http://www.jksemi.com>

For additional information, please contact your local Sales Representative.

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